	APPLICA	BLE STAN	DARD									
RATING				-55 °C TO 85	°C (1)	TE	MPERAT			-10 °C TO 60	°C (2)	
CURRENT 0.5 A SIGNAL CONTACT) 20 REQUIREMENTS QT AT	RATING	VOLTAGE		100 V AC		RA	NGE			40 % TO 70	% ⁽²⁾	
SPECIFICATIONS		CURRENT		0.5 A (SIGNAL CONTACT) (3) A R						RELATIVE HUMIDITY	′ 85% ı	max
ITEM				3 A (MF CONTACT	(MF CONTACT)					(NOT DEWED)		
ITEM				SPEC	IFIC <i>A</i>	ATION	IS					
CONSTRUCTION SECRETARY CONFIRMED VISUALLY AND BY MEASURING INSTRUMENT. ACCORDING TO DRAWING. X X X X X X X X X	IT	EM						RE	ัดบเ	REMENTS	Тот	ТАТ
GENERAL EXAMINATION VISUALLY AND BY MEASURING INSTRUMENT ACCORDING TO DRAWING. X X X X X X X X X			1				1				1~.	1
MARKING			IVISUALL	VISUALLY AND BY MEASURING INSTRUMENT				ACCORDING TO DRAWING				
CONTACT RESISTANCE							The series is a protection.					+
CONTACT RESISTANCE	ELECTRIC CHARAC		TERISTICS								1	1
INSULATION RESISTANCE 250 V DC 1000 MQ MIN							λ					_
VOLTAGE PROOF 300 V AC FOR 1 min. NO FLASHOVER OR BREAKDOWN. X	INSULATION RESISTANCE		250 V DC									
MECHANICAL CHARACTERISTICS MEASURED BY APPLICABLE CONNECTOR. INSERTION FORCE: 40 N MAX.												<u> </u>
INSERTION AND WITHDRAWAL FORCES MECHANICAL OPERATION SOO TIMES INSERTIONS AND EXTRACTIONS. SINGLE AMPLITUDE: 0.75 mm, 10 CYCLES SIGNAL CONTACT: 1:00 m Q MAX. MF CONTACT: 1:00 m Q MAX.							THE TEXAL PROPERTY OF THE PROP					
MITHORAWAL FORCES								TINSERTION FORCE: 40 N MAX				
SIGNAL CONTACT : 100 m 2 Max			MEXICONED BY ANY EIGHBEE CONNECTION.			•						
SIGNAL CONTACT : 100 m 2 Max	MECHANICA	\L	500 TIMES INSERTIONS AND EXTRACTIONS.			NS.						† <u>–</u>
2. NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	OPERATION	OPERATION					SIGNAL CONTACT : 100 m Ω MAX. A					
VIBRATION FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min 10 CYCLES FOR 3 DIRECTIONS. 2) NO ELECTRICAL DISCONTINUITY OF 1 1 1 1 1 1 1 1 1 1							MF CONTACT : $40 \text{ m}\Omega \text{ MAX}$.					
FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE: 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.												
SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.							OF PARTS.					
FOR 3 DIRECTIONS. \$HOCK			· ·				① NO	① NO ELECTRICAL DISCONTINUITY OF ×				
SHOCK 490 m/s², DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS. ENVIRONMENTAL CHARACTERISTICS DAMP HEAT (STEADY STATE) EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h. (STEADY STATE) (STEADY							1 '					
AT 3 TIMES FOR 3 DIRECTIONS.												-
ENVIRONMENTAL CHARACTERISTICS DAMP HEAT (STEADY STATE) EXPOSED AT 40 ± 2 °C, 90 ~ 95 %, 96 h. (STEADY STATE) RAPID CHANGE OF TEMPERATURE TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER WITHIN 2~3 MIN) (ICST STANDARD: JIS C 60068) RESISTANCE TO SOLDERING HEAT PEAK TIME: 280 °CMAX REFLOW TIMP: 220 °CMIN FOR 60sec 2) SOLDERING IRONS: 360 °C MAX. FOR 5 sec. SOLDERABILITY COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED. A PPROVED H. SANO (HECKED DATE A PPROVED H. SANO (H. HIROKAWA OP. 09. 09. 15 FOR THE UNISCED REPODED SECROFICATION OPTORAGE* MEANS A LONG-TERM STORAGE STATE FOR THE UNISCED PRODUCT BEFORE ASSEMBLY TO PCB. OPTIME WATER OF THE PROPOSED OF THE CONTACT. OPTIME WATER OF THE PROPOSED SECROPICATION OPTIME WATER OF THE PROPOSED SECROPICATION OPTIME WATER OF THE OUNSED PRODUCT BEFORE ASSEMBLY TO PCB. OPTIME WATER OF THE OUNSED PRODUCT BEFORE ASSEMBLY TO PCB. OPTIME WATER OF THE OUNSED PCD OUT BEFORE ASSEMBLY TO PCB. OPTIME WATER OF THE OUNSED PCD OUT BEFORE ASSEMBLY TO PCB. OPTIME WATER OF THE OUNSED PCD OUT BEFORE ASSEMBLY TO PCB. OPTIME WATER OF THE OUNSED PCD OUT BEFORE ASSEMBLY TO PCB. OPTIME WATER OUT BEFORE ASSEMBL			1				05	OFFARTS.				
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